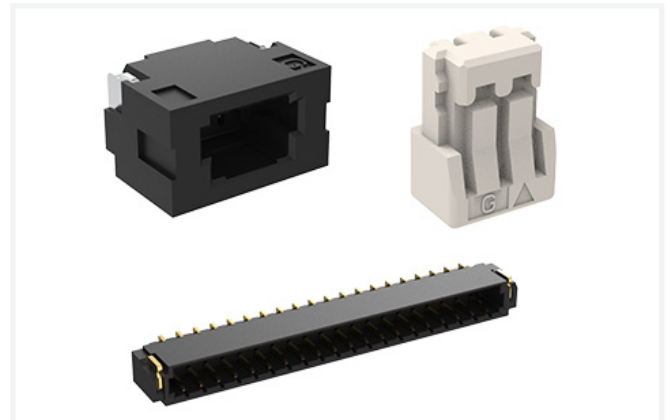


AgilLink™ 0.8mm Wire-to-Board (G855 Series)

CUSTOMIZABLE SHROUDED WIRE-TO-BOARD HEADER

AgilLink™ 0.8mm wire-to-board connector is the most common solution for transferring low power and signal. This series can carry a maximum current rating of 1A. Amphenol offers a comprehensive range of these headers including, V/T SMT, and R/A SMT to meet various customer requirements. The compactness of the connectors allows for extensive usage in consumer applications.

- Compactness for easy-to-fit the small equipment
- Cost-effective
- Simplicity of installation
- Supports PiP process
- Saving space



TARGET MARKETS



FEATURES

- 0.8mm pitch wire to board solution
- Various mounting options including vertical SMT, right angle SMT
- High temperature thermoplastic material
- Tape and reel packaging option
- Mates with WTB G855H/G855C
- RoHS compliance and halogen-free

BENEFITS

- Low profile feature can save the space
- Ease in choosing board mating configurations
- Re-flow compatible
- Supports PiP process
- Mutually compatible for wire-to-board
- Meets environmental, health and safety requirements

TECHNICAL INFORMATION

MATERIAL

- Housing: High temperature thermoplastic, UL94V-0
- Contact: Copper Alloy, selective Gold or Tin plating on contact area, Gold flash or Tin plating on solder tail and Nickel under-plated overall

MECHANICAL PERFORMANCE

- Contact Retention Force: Base on individual P/N
- Durability: 30 cycles
- Insertion Force: Base on individual P/N
- Withdrawal Force: Base on individual P/N
- Vibration: 1µs max., EIA 364-28
- Mechanical shock: 1µs max., EIA 364-27

ELECTRICAL PERFORMANCE

- Current Rating: 1A AC/DC
- Voltage Rating: 50VAC/VDC
- Temperature: -40°C to +85°C
- Contact Resistance: 20mΩ max.
- Insulation Resistance: 100MΩ min.

PACKAGING

- Tape and reel
- Bag

ENVIRONMENTAL

- Thermal shock: a) -55°C ~ 30 minute. b) +85°C ~ 30 minute, 10 cycles, EIA 364-32
- Humidity: 60°C, 90~95%RH, 240 hours, EIA 364-31
- Heat Resistance: 85°C, 96 hours, EIA 364-17
- Cold Resistance: -40°C, 96 hours, EIA 364-17
- Solder-ability: 95% min. solder coverage, EIA 364-52
- Resistance to Soldering Heat: Peak temperature: 260°C max., 10 seconds max.

TARGET MARKETS/APPLICATIONS



Communications



Consumer



Server Storage



Industrial & Instrumentation



Medical

PART NUMBERS

Part Numbers	Description	3D	2D
G855A20201TEU	Wire-to-Board 0.8mm Pitch R/A SMT, 1x20Pin, G/F, LCP, Color-Black, Halogen-free	G855A20201TEU	G855AXX2XXTEU
G855A02101THR	Wire-to-Board 0.8mm Pitch STR SMT, 1x2Pin, Matte Tin, LCP, Color-Black, Halogen-free	G855A02101THR	G855AXX1XXTHR
G855H021T1HR	G855 Series, 0.8mm Pitch, Cable Side Housing, 1x2Pin, LCP, Color-Cream	G855H021T1HR	G855HXXX1T1HR